



SOT619-1

plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; 7 mm x 7 mm x 0.85 mm body

5 February 2018

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	13-12-2017
Manufacturer package code	SOT619-1

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	-	-	0.85	1	mm
A ₂	package height	-	-	0.85	-	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	48	-	A/A

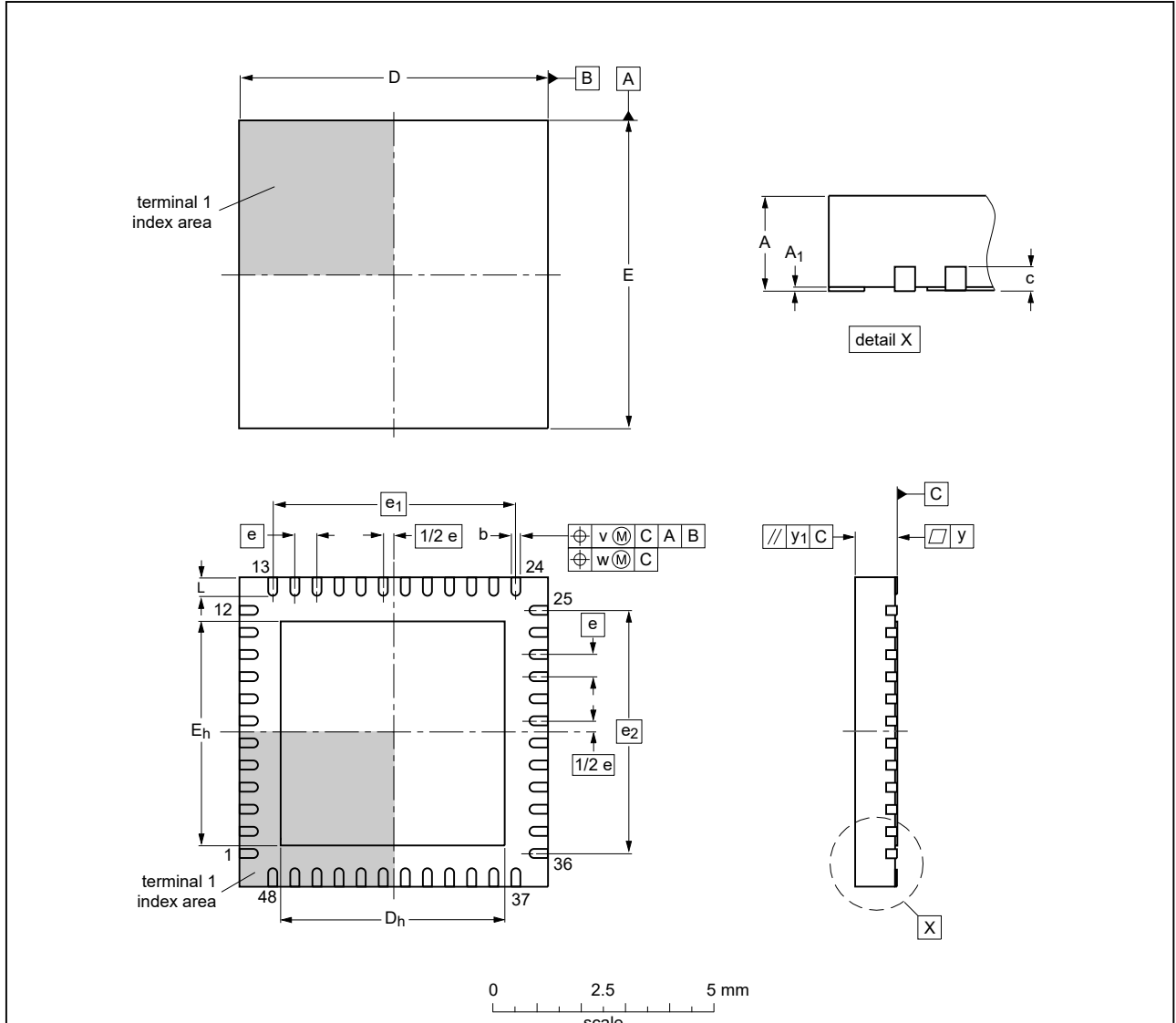


plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; 7 mm x 7 mm x 0.85 mm body

2. Package outline

HVQFN48: plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 7 x 7 x 0.85 mm

SOT619-1



Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A	A ₁	b	C	D	D _h	E	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
max	1.00	0.05	0.30		7.1	5.25	7.1	5.25				0.5				
mm nom	0.85	0.02	0.21	0.2	7.0	5.10	7.0	5.10	0.5	5.5	5.5	0.4	0.1	0.05	0.05	0.1
min	0.80	0.00	0.18		6.9	4.95	6.9	4.95				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

sot619-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT619-1		MO-220			-02-10-18- 12-11-22

Fig. 1. Package outline SOT619-1

plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; 7 mm x 7 mm x 0.85 mm body

3. Soldering

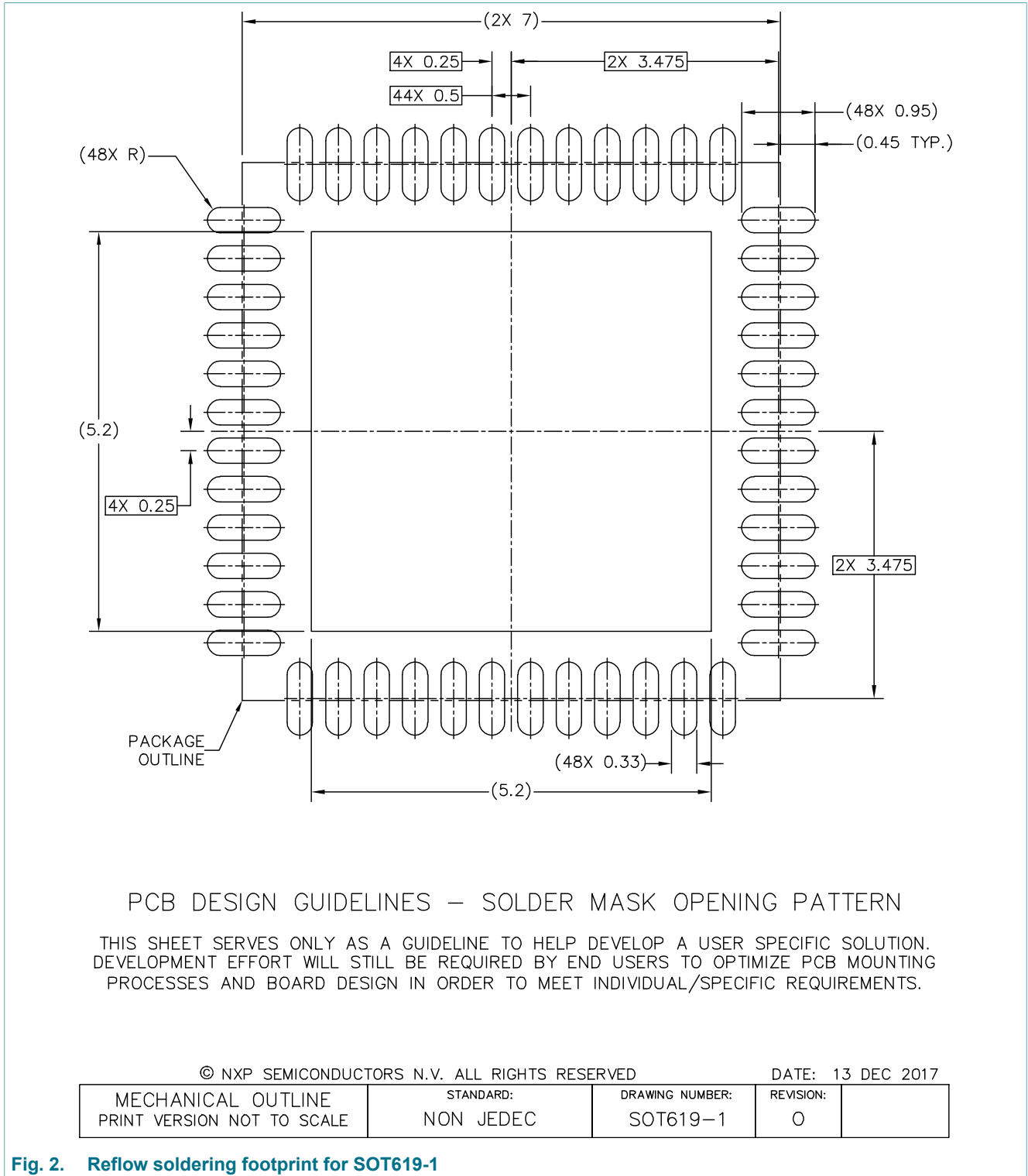
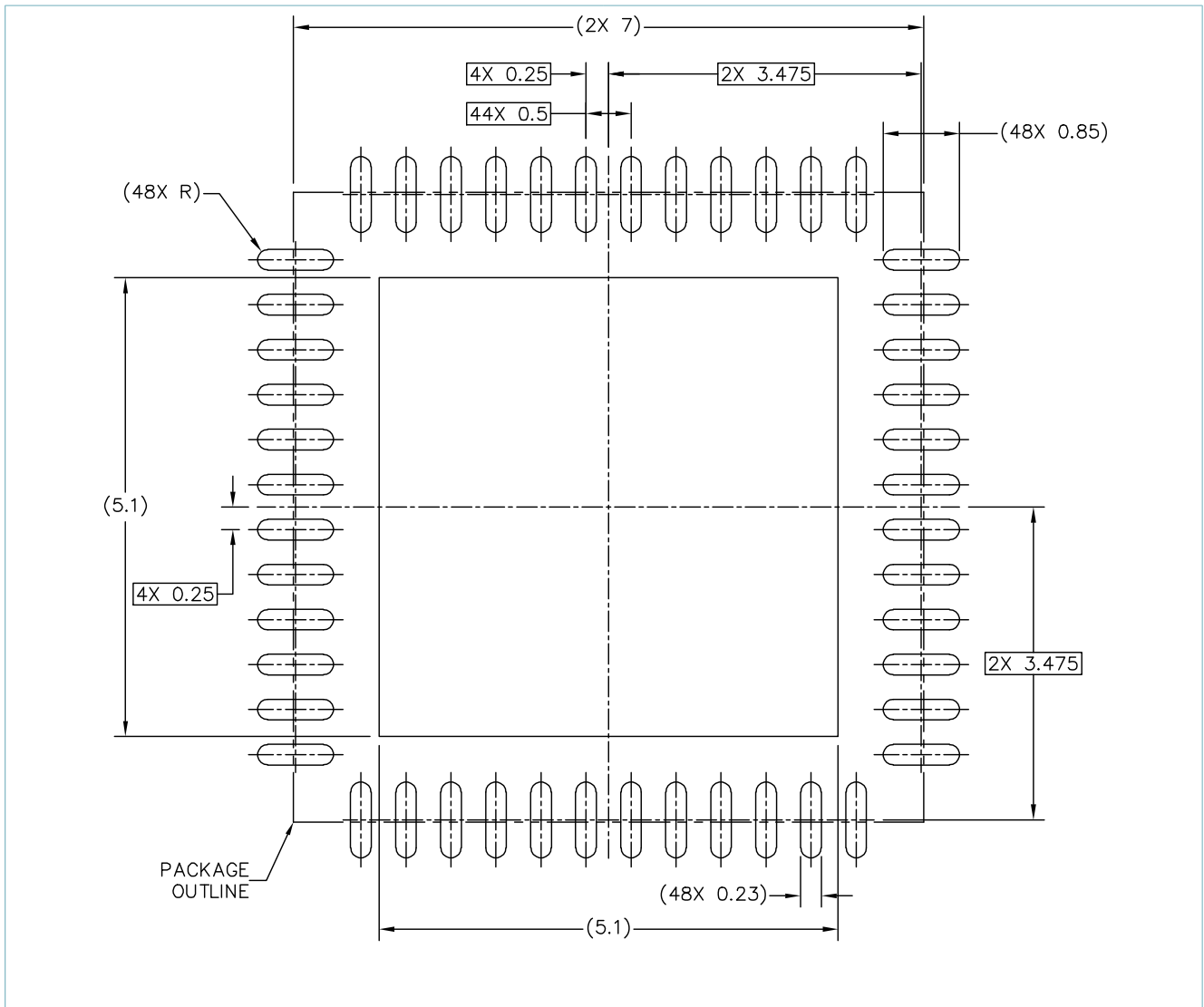


Fig. 2. Reflow soldering footprint for SOT619-1

plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; 7 mm x 7 mm x 0.85 mm body



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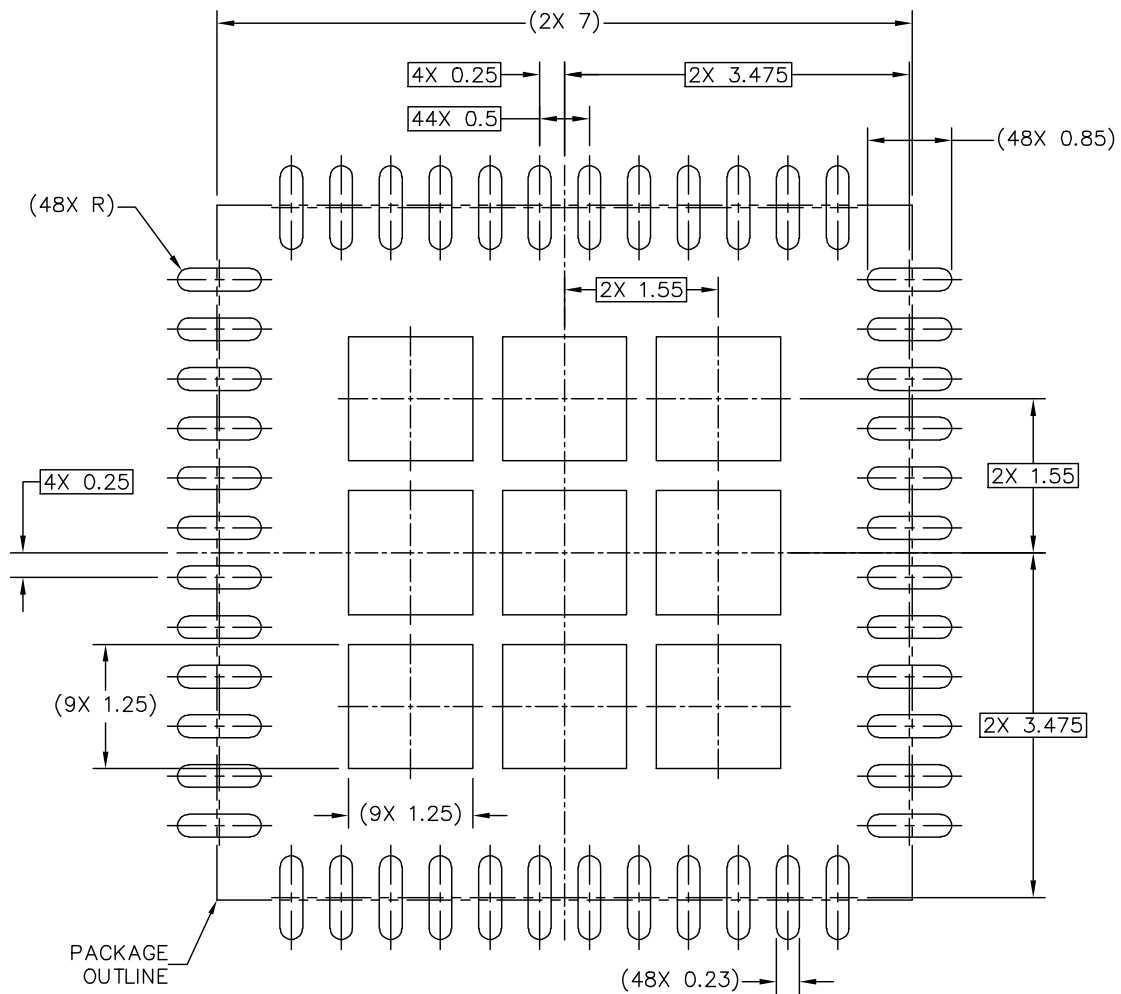
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DATE: 13 DEC 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT619-1	REVISION: 0	
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Fig. 3. Reflow soldering footprint part2 for HVQFN48 (SOT619-1)

plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; 7 mm x 7 mm x 0.85 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Fig. 4. Reflow soldering footprint part3 for HVQFN48 (SOT619-1)

plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; 7 mm x 7 mm x 0.85 mm
body

4. Legal information

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